3.2mmx1.6mm SMD CHIP LED LAMP





Features

- Ideal for indication light on hand held products
- Long life and robust package
- Standard Package: 2,000pcs/ Reel
- \bullet MSL (Moisture Sensitivity Level): 3
- RoHS compliant







ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Package Schematics POLARITY MARK 3.2(0.126) 2(0.079) 1.9(0.075) 0.5(0.02)

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.2(0.008")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)	M2DG (InGaN)	Unit		
Reverse Voltage V ₁		5	V	
Forward Current	I_{F}	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	100	mA mW	
Power Dissipation	P_{D}	120		
Operating Temperature	$T_{\rm A}$	-40 ~ +85		
Storage Temperature	Tstg	-40 ~ +85		
Electrostatic Discharge Threshold (HBM)	450	V		

	M2DG (InGaN)	Unit
$ m V_F$	3.2	V
$ m V_F$	4	V
${ m I}_{ m R}$	50	uA
λΡ	520*	nm
λD	525*	nm
$\triangle \lambda$	35	nm
C	100	pF
	V_{F} I_{R} λP λD $\triangle \lambda$	$\begin{array}{c cc} & \text{(InGaN)} \\ & V_F & 3.2 \\ \\ & V_F & 4 \\ \\ & I_R & 50 \\ \\ & \lambda P & 520^* \\ \\ & \lambda D & 525^* \\ \\ & \triangle \lambda & 35 \\ \\ \end{array}$

Part Number	Emitting Color	Emitting Material	Lens-color	$\begin{array}{c} \text{Luminous Intensity} \\ \text{CIE127-2007*} \\ \text{(I_F=20mA)} \\ \text{mcd} \end{array}$	Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min. typ.		

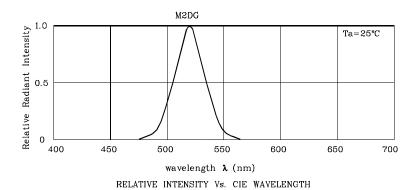
				min.	typ.		
ZM2DG55W-1	Green	InGaN	Water Clear	400*	745*	520*	120°

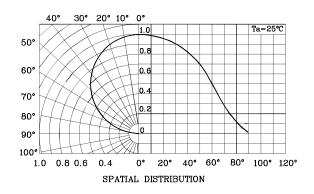
^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.



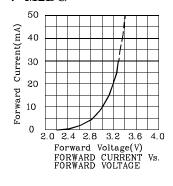


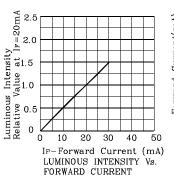


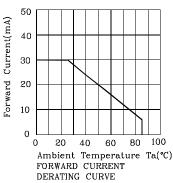


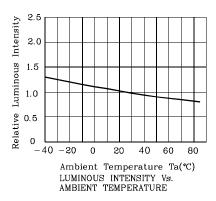


❖ M2DG



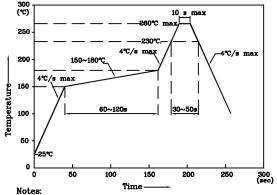






LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

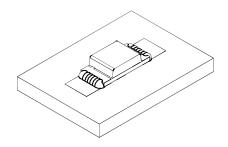


- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions

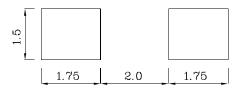




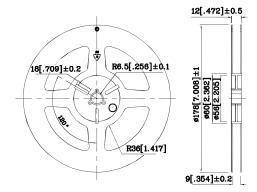
❖ The device has a single mounting surface. The device must be mounted according to the specifications.



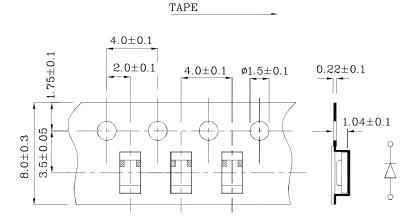
❖ Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



❖ Reel Dimension



❖ Tape Specification (Units:mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

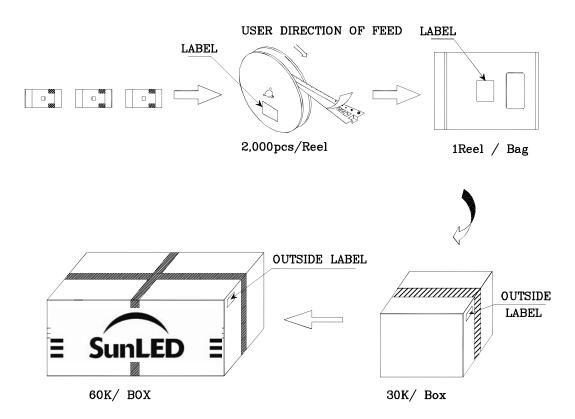
- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

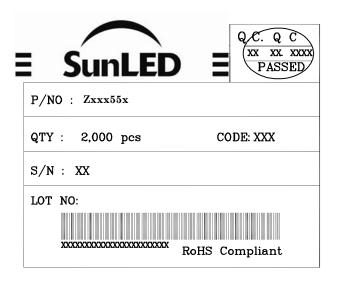
Note: Accuracy may depend on the sorting parameters.





PACKING & LABEL SPECIFICATIONS





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